

Operation: 沉板式 (沉深 2.0mm) D+S 结构 & 3.1Type-C 连接器 (24PIN)



ITEM NO.: MC-313S (Consumer Electronics)

(L10.3×W9.15×H 3.65 & DUL SMT LOW PCB TYPE)

Type-C CONNECTORS



邀您使用(微信)小程序
硕方电子开关&连接器选型手册
手机扫码即可进入...

Technical parameter

外焊贴片式 SMT

侧向导入 LATERAL

精密部品 NICETY

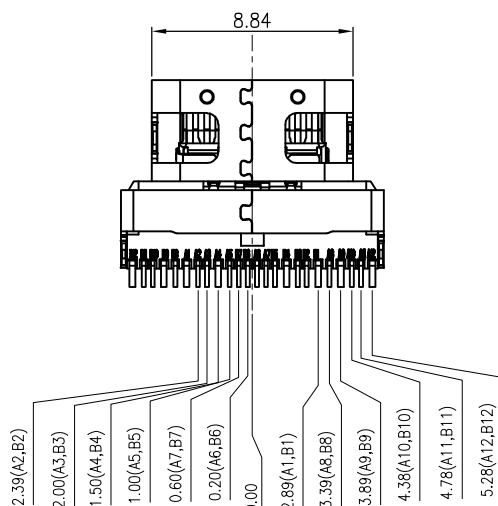
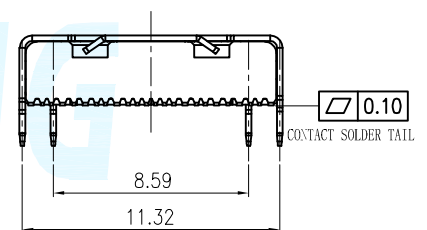
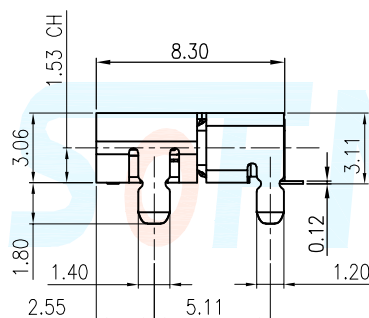
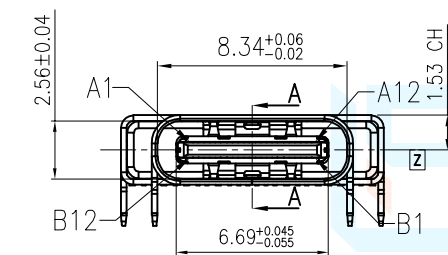
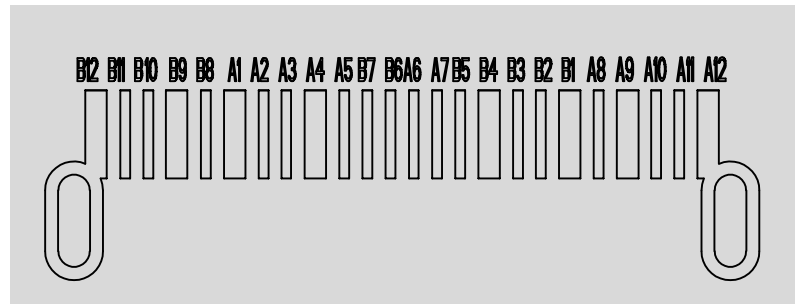
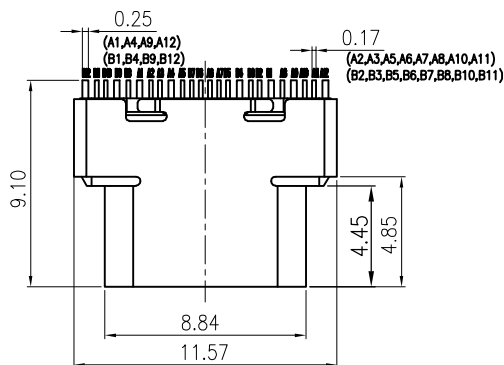
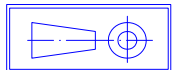
可靠 STABILIZE

环保材质 RoHS

PROJECT	LEVEL	A[better product]		B[average product]
Electrical Properties	Contact Rating	5A, 24V DC		
	Initial Contact Resistance	30mΩ max.	50mΩ max.	
	Insulation Resistance	100MΩ min.500V DC	Skey/PD: 100MΩ min.300V DC	
	Withstand Voltage	500V AC for 1 minute	350 V AC for 1 minut	
Durable Performance	There No Load	6,500 Cycles	5,500 Cycles	
	Rated Load	5,500 Cycles	4,500 Cycles	
	Storage Temp	25℃/50℃RH (Operating temperature: -35℃～+75℃)		

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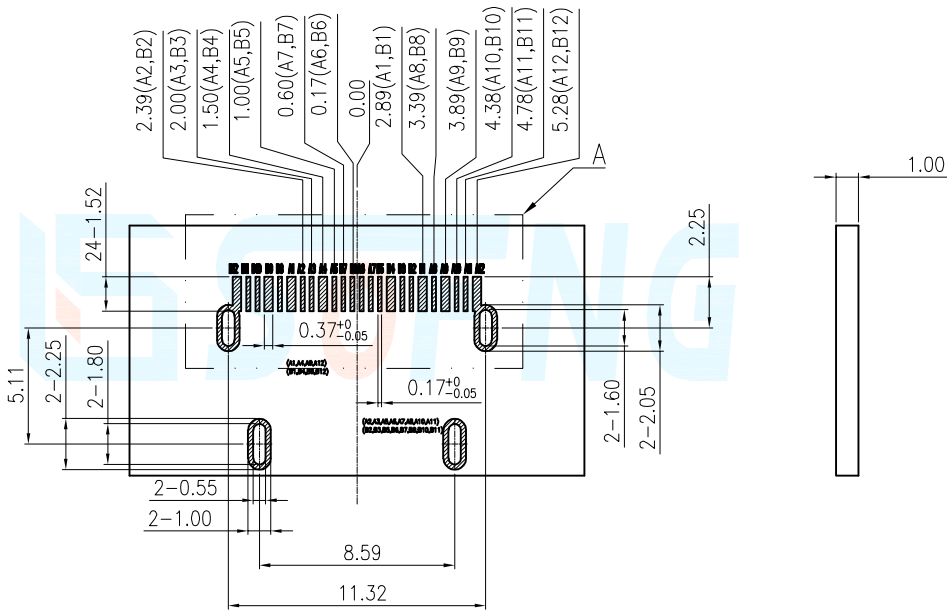
Unit:mm



Material declaration

No	NAME	MATERIAL	REMARKS
①	TERMINAL HOUSING 基座	HIGH TEMPERATURE PLASTIC	BLACK/NATURE/GREEN
②	SPRING 弹片	STAINLESS 【G/F】 t=0.10	0.25 μm Ni PLATED OVERALL;
③	IRON HOUSING 胶芯	HIGH TEMPERATURE PLASTIC	UL 94V-0,COLOR:BLACK;
④	SHELL 外壳	STAINLESS 【G/F】 t=0.30	Ni PLATED
⑤	DUST COVER 防护盖	HIGH TEMPERATURE PLASTIC	UL 94V-0,COLOR:BLACK;
⑥	CONTACT 接触端子	COPPER ALLOY 【G/F】 t=0.15	C5191R-H (1u" MIN)

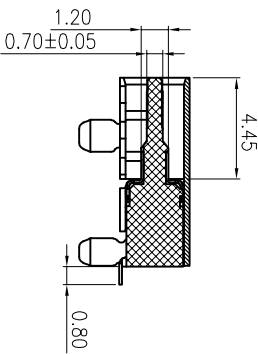
Operating Force	Inward	8. 0~20. 0N. (1N.=100gram-force)	Solder-ability (Max.)	IR Reflow:255℃, 5sec.	Manual :350℃, 3sec.
	Exiting	8. 0~20. 0N. (1N.=100gram-force)			



DECIMALS	ANGLES
.X :±0.25	X.° :±1.5°
.XX :±0.15	X.X° :±1.0°
.XXX :±0.10	.XXX° :±0.5°

PIN ASSIGNMENTS

PIN	Signal NAME	Description	PIN	Signal NAME	Description
A 1	GND	Ground return	B12	GND	Ground return
A 2	SSTXp1	Positive half of first SuperSpeed TX differential pair	B11	SSRXp1	Positive half of second SuperSpeed RX differential pair
A 3	SSTXn1	Negative half of first SuperSpeed TX differential pair	B10	SSRXn1	Negative half of second SuperSpeed RX differential pair
A 4	V BUS	Bus Power	B 9	V BUS	Bus Power
A 5	CC1	Configuration Channel	B 8	SBU2	Sideband Use (SBU)
A 6	Dp1	Positive half of the USB 2.0 differential pair-Position 1	B 7	Dn2	Negative half of the USB 2.0 differential pair-Position 2
A 7	Dn1	Negative half of the USB 2.0 differential pair-Position 1	B 6	Dp2	Positive half of the USB 2.0 differential pair-Position 2
A 8	SBU1	Sideband Use (SBU)	B 5	CC2	Configuration Channel
A 9	V BUS	Bus Power	B 4	V BUS	Bus Power
A10	SSRXn2	Negative half of second SuperSpeed RX differential pair	B 3	SSTXn2	Negative half of first SuperSpeed TX differential pair2
A11	SSRXp2	Positive half of second SuperSpeed RX differential pair	B 2	SSTXp2	Positive half of first SuperSpeed TX differential pair2
A12	GND	Ground return	B 1	GND	Ground return



SECTION A-A

注記 NOTICE

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